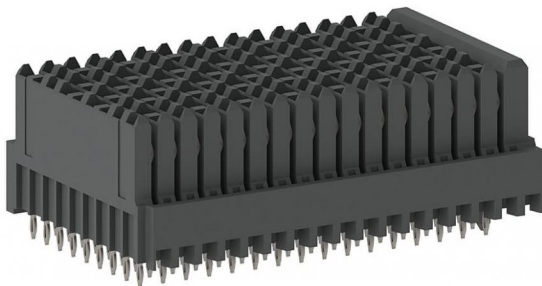


Product Data Sheet

Velox 16-right,
Part No. 308-51100-41



Bestückplan / pin arrangement

X = bestückt / loaded
= nicht bestückt / not loaded

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
j	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
n	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
g	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
f	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
e	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
d	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
c	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
b	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
a	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X



Illustration similar



Perpendicular



Press-fit



High Speed



Rugged

- plating Press-fit Zone: SnPb
- fully loaded (144 contacts)
- termination technology: Press-fit
- pitch 1.8 mm
- data transfer rate 10 Gbit/s



» to product on www.ept.de



» to product group Velox Highspeed Backplane

Product Data Sheet

Velox 16-right,
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Technical Specifications

Basics

Specification	VITA 46
No. of Contacts	144
Termination Technology	Press-fit
Termination Length	1.62 mm
Operating Temperature Range	-55°C to +105°C

Material

Insulator Material	LCP, UL 94 V-0
CTI value <i>IEC 60112</i>	175
Contact Material	Phosphor Bronze
Plating	1.27 µm Au over Ni on contact area, SnPb on Press-fit zone

Mechanical

Pitch	1.8 mm
Mating Force per Pin	max. 0.75 N
Separating Force per Pin	min. 0.15 N
Durability	200 mating cycles

Electrical

Operational Current	1.0 A (<30°C)
Operational Voltage	50 VAC Peak or DC
Contact Resistance	max. 80 mΩ
Clearance and Creepage	≥ 0.7 mm
Insulation Resistance	min. 1000 MΩ
Test Voltage	500 V (AC/DC)
Data Transfer Rate	10 Gbit/s

Approval / Compliance

UL file	E130314
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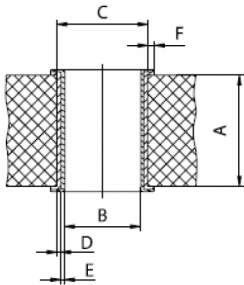
Product Data Sheet

Velox 16-right,
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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	imm. Sn printed circuit boards
Nominal Hole	Ø 0.56 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 0.56 ±0.05 mm
C Drill Hole	0.65 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	imm. Sn plating, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au printed circuit boards
Nominal Hole	Ø 0.56 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 0.56 ±0.05 mm
C Drill Hole	0.65 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Product Data Sheet

Velox 16-right,
Part No. 308-51100-41



Modifications

Available on request

- different custom loaded versions

Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)

[» 3D IGES](#)

[» 3D STEP](#)

[» 3D PDF](#)